



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1503-02 (R1) DATE: 2-Oct-2015		MEANS OF DISTINGUISHING CHANGED DEVICES: ☐ Product Mark Lot # will have: ☒ Back Mark "A" prefix for OSET, Taiwan ☐ Date Code ☐ Other
Product Affected: TSSOP-28 Refer to Attachment II for the affected part numbers		
Date Effective: 2-Jan-2016		
Contact: IDT PCN DESK	Attachment: ☒ Yes ☐ No	
E-mail: pcndesk@idt.com	Samples: Please contact your local sales representative for sample request.	

DESCRIPTION AND PURPOSE OF CHANGE:

- | | |
|--|--|
| ☐ Die Technology | Revision 1: This notification is a follow-up letter advising the completed qualification results as shown in Attachment I. |
| ☐ Wafer Fabrication Process | |
| ☐ Assembly Process | |
| ☐ Equipment | |
| ☐ Material | |
| ☐ Testing | This notification to advise our customers that IDT is transferring the affected products assembled at Amkor, Philippines (ATP) to OSET, Taiwan (OSET) as ATP will discontinue their assembly tooling for this product. |
| ☒ Manufacturing Site | |
| ☐ Data Sheet | There is no change to moisture sensitive level. |
| ☐ Other | Attachment I details the qualification data for this change
Attachment II details the affected part number list. |

RELIABILITY/QUALIFICATION SUMMARY:

Qualification has been successfully completed. There is no change in MSL rating.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	☐ Approval for shipments prior to effective date.
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT I - PCN # : A1503-02 (R1)

PCN Type: Manufacturing Site - Transfer Assembly Location

Data Sheet Change: None

Detail Of Change:

This notification is to advise our customers that IDT is transferring the affected products assembled at Amkor, Philippines (ATP) to OSET, Taiwan (OSET) as ATP will discontinue their assembly tooling for this product. Presently, OSET is a qualified IDT Subcontractor.

The material set details of the current and new assembly location is as shown in Table 1.

There will be no change in form, fit and function of the products including RoHS compliance and MSL rating.

During the transition period, IDT will continue to support customer shipments with inventory built at ATP facility and does not anticipate any impact on the product availability.

We request you to acknowledge receipt of this notification within 30 days of the date of this PCN notification. If you require samples to conduct an evaluation, please make your sample request within 30 days as samples are not built ahead of the change. Please contact your IDT sales representative to request samples or for additional information.

Table 1: Assembly Material Sets for The Existing and New Assembly Locations

	Current Assembly: ATP	New Assembly: OSET
Die Attach	Ablestik 8290	EN4900GC
Wire	Au or Cu wire	Au or PdCu wire
Mold Compound	EME G700K	CEL- 9200HF



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ATTACHMENT I - PCN # : A1503-02 (R1)

Qualification Test Plans and Results :

Qual Plan & Results: The qualification was performed in accordance with JEDEC47 recommended tests

Qual Vehicle: TSSOP-28 (3 lots)

Test Description	Test Method	Test Results (SS / Rej)		
		Lot 1	Lot 2	Lot 3
* HAST - Unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	25/0	25/0	25/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	25/0	25/0	25/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	25/0	25/0	25/0

Note:

* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test



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ATTACHMENT II - PCN # : A1503-02 (R1)

Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
841602AGILF	841604AGILF	841664AGILF	93716AGLF
841602AGILFT	841604AGILFT	841664AGILFT	93716AGLFT
841604AGI-01LF	841654AGILF	87604AGILF	93716BGLF
841604AGI-01LFT	841654AGILFT	87604AGILFT	93716BGLFT